



Product data sheet

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P4200SC-MS Semiconductor Compiance



Features

Low capatcitance Cannot be damaged by voltage Will not fatigue Eliminate voltage overshoot Glass passivated junction Halogen free and RoHS compliant



SMB

Mechanical Data CASE: SMB(DO-214AA) Molded Plastic UL Flammability Classification Rating 94V0 Mounting Position:Any

Maximum Ratings & Thermal Characteristics

(Ratings at 25 $^{\circ}$ C ambient temperature unless otherwise specified.)

Parameter	Symbol	Value	Units	Remarks
Peak Pulse Voltage	V _{PP}	6000	V	10/700us
Peak Pulse Current	PP	100	А	10/1000us
Peak Pulse Current	I _{PK}	400	А	8/20us
Peak One-cycle Surge Current	I _{TSM}	30	А	60Hz
Rate of Rise of Current	di/dt	500	A/us	
Typical Thermal Resistance Junction to Lead	$R_{ extsf{ hetaJL}}$	20	°C/W	
Typical Thermal Resistance Junction to Ambient	$R_{ extsf{ heta}JA}$	100	°C/W	
Operating Temperature Range	TJ	-40 to 150	°C	
Storage Temperature Range	T _{STG}	-55 to 150	°C	

Electrical Characteristics

(Ratings at 25 $\,^\circ\!\!\mathbb{C}\,$ ambient temperature unless otherwise specified).

P/N	Mark	Vs @100KV/S V MAX	I_{S_LMT mA}	V T @ Ι _Τ V MAX	I т А	I _D @V _D uA MAX	V _D V	C ₀ @1MHz,2V _{DC} pF TYP	I н mA MAX
P4200SC-MS	P42C	520	800	4	2.2	5	400	45	100



P4200SC-MS HF Compiance

Ratings and Characteristic Curves





Fig.2 - Normalized DC Holding Current vs. Case Temperature





P4200SC-MS HF Semiconductor Compiance

PACKAGE MECHANICAL DATA



	Dimensions					
Ref.	Millir	neters	Inches			
	Min.	Max.	Min.	Max.		
Α	4.25	4.75	0.167	0.187		
В	3.30	3.94	0.130	0.155		
С	1.85	2.21	0.073	0.087		
D	0.76	1.52	0.030	0.060		
Е	5.08	5.59	0.200	0.220		
F	0.051	0.203	0.002	0.008		
G	0.15	0.31	0.006	0.012		
Н	2.11	2.44	0.083	0.096		
J	6.80		0.270			
К		2.60		0.100		
L	2.40		0.090			

REEL SPECIFICATION

P/N	PKG	QTY
P4200SC-MS	SMB	3000



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